

Description

The 5P35021 is the latest VersaClock programmable clock generator and is designed for low-power, consumer, and high-performance PCI Express applications. The 5P35021 device is a 3 PLLs architecture design; each PLL is individually programmable and allows up to 3 unique frequency outputs.

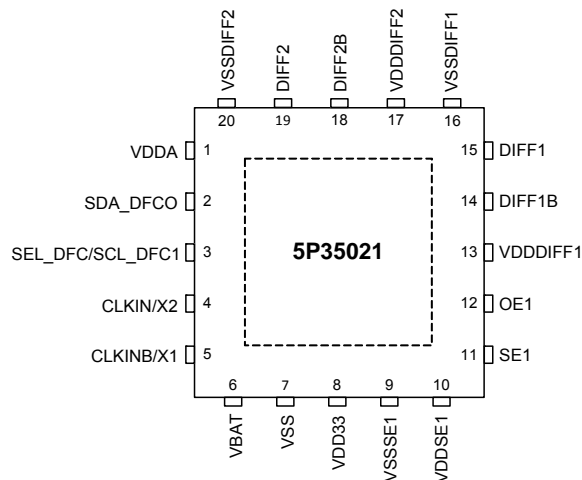
The 5P35021 has built-in unique features such as Proactive Power Saving (PPS), Performance-Power Balancing (PPB), Overshot Reduction Technology (ORT) and extreme low power DCO. An internal OTP memory allows the user to store the configuration in the device. After power up, the user can change the device register settings through the I²C interface when I²C mode is selected. It also has programmable VCO and PLL source selection to allow the user to do power-performance optimization based on the application requirements.

The device provides one single-ended output and two pairs of differential outputs that support LVCMOS, LVPECL, LVDS and LPHCSL. The low power 32.768kHz clock is supported with only less than 2μA current consumption for system RTC reference clock.

Typical Applications

- PCIe Gen1/2/3 clock generator
- Consumer application crystal replacements
- SmartDevice, Handheld, Computing and Consumer applications

Pin Assignment



Features

- Configurable OE pin function as OE, PD#, PPS or DFC control function
- Configurable PLL bandwidth/minimizes jitter peaking
- PPS: Proactive Power Saving features save power during the end device power down mode
- PPB: Performance- Power Balancing feature allow user to minimum power consumption base on required performance
- DFC: Dynamic Frequency Control feature allows user to program up to 4 difference frequencies and switch dynamically
- Spread spectrum clock support to lower system EMI
- Store user configuration into OTP memory
- I²C interface

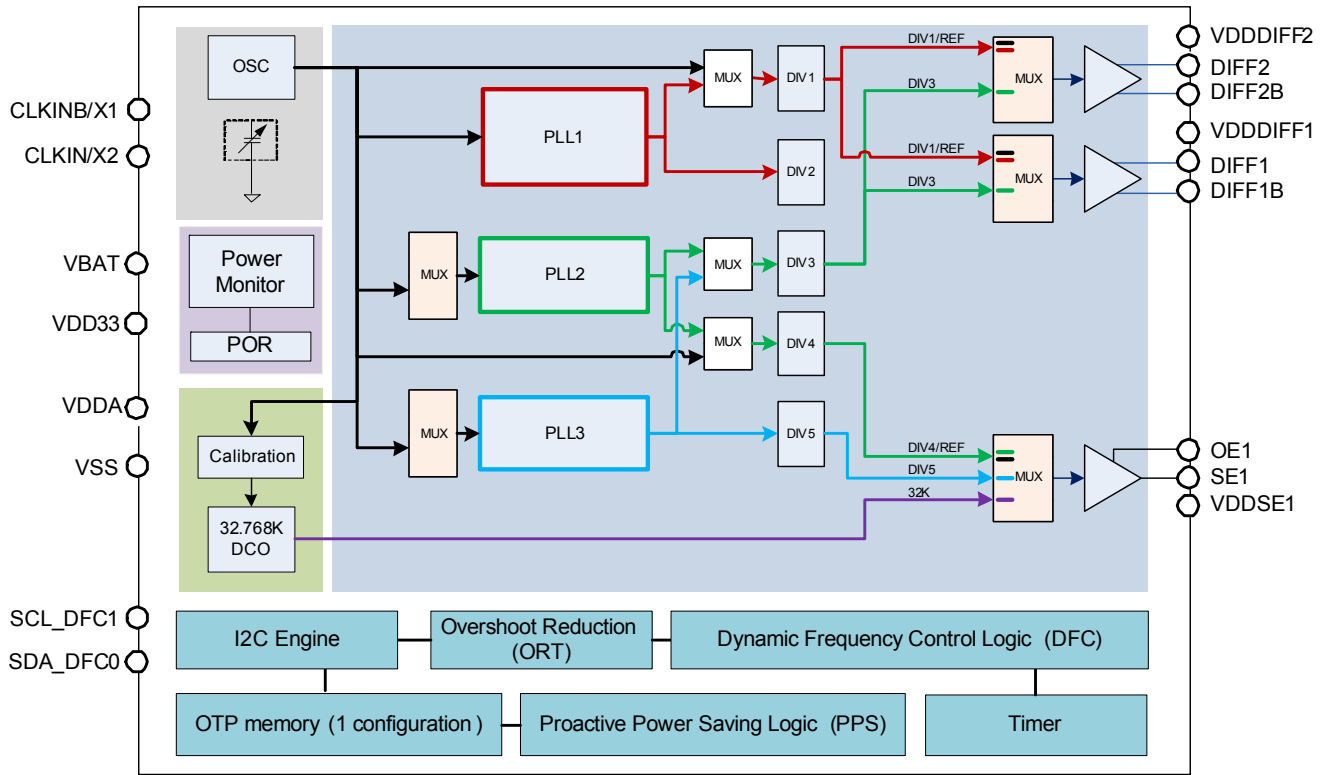
Key Specifications

- PCIe clocks phase jitter: PCIe Gen3
- Differential clocks < 3 ps rms jitter integer range 12kHz–20MHz
- < 2μA DCO to generate 32.768kHz clock

Output Features

- 2 DIFF outputs with configurable LPHSCL, LVDS, LVPECL, LVCMOS output pairs. 1MHz–500MHz (160MHz/ with LVCMOS mode)
- 1 LVCMOS output: 1MHz–160MHz
- Maximum 5 LVCMOS outputs as 1 × SE + 2 × DIFF_T/C as LVCMOS
- Low Power 32.768kHz clock supported on SE1

Functional Block Diagram



Power Group

Power supply table	SE	DIFF	DIV	MUX	PLL	DCO	REF	Xtal
	VDDSE1	SE1						
VDDDIFF1		DIFF1	DIV3/4	MUXPLL2	PLL2			
VDDDIFF2		DIFF2	DIV1	MUXPLL1				
VDD33			DIV5		PLL3	DCO	REF	Xtal
VBAT						DCO		Xtal
VDDA			DIV2		PLL1			

* VDDSEx for non-32kHz outputs should be OFF when VDDA/VDD3 turn OFF, VBAT mode only support 32.768kHz outputs from SE1-3.

* VBAT power ramp up should be same or earlier than other VDD power rail.

Output Source Table

Source:	Outputs:		
	SE1	DIFF1	DIFF2
Xtal REF	Xtal REF	Xtal REF	Xtal REF
32.768kHz	32.768kHz		
PLL1		PLL1	PLL1
PLL2		PLL2	PLL2
PLL3		PLL3	PLL3

Output Source Selection Register Setting Table

SE1	B36<4>	B36<3>	B31<1>	B29<3>
From 32K	0	1	0	0
From PLL3 + Divider 5	1	0	0	0
From PLL2 + Divider 4	1	1	1	0
From REF + Divider 4	1	1	0	1

DIFF1	B34<7>	B0<3>
From PLL1 + Divider 1	0	0
From PLL2 + Divider 3	1	0
From REF + Divider 1	0	1

DIFF2	B35<7>	B0<3>
From PLL1 + Divider 1	0	0
From PLL2 + Divider 3	1	0
From REF + Divider 1	0	1

Glossary of Features

Term	Function Description	Apply to
DFC	Dynamic Frequency Control, from selected PLL to support four VCO frequencies, means two different output frequencies by assign H/W pin state changes.	PLL2
ORT	Overshoot Reduction, when the DFC dynamic frequency change is functional, the VCO change frequency smoothly to target frequency without overshoot or under shoot.	PLL2
OE	Output Enable function, each output can be controlled by assigned OE pin, the dedicated OE pin can be OTP programmable as Global Power Down function (PD#) or Output enable (OE) or proactive power saving function (PPS) or RESET pin function.	OE1
SS	Spread spectrum clock.	PLL1/PLL2
Slew Rate	LVC MOS outputs with slew rate control - slow and fast.	LVC MOS
PPS	Proactive Power Saving, utilize OE pin as monitor pin for end device X2 clock status, details see PPS function .description	SE1

Pin Descriptions

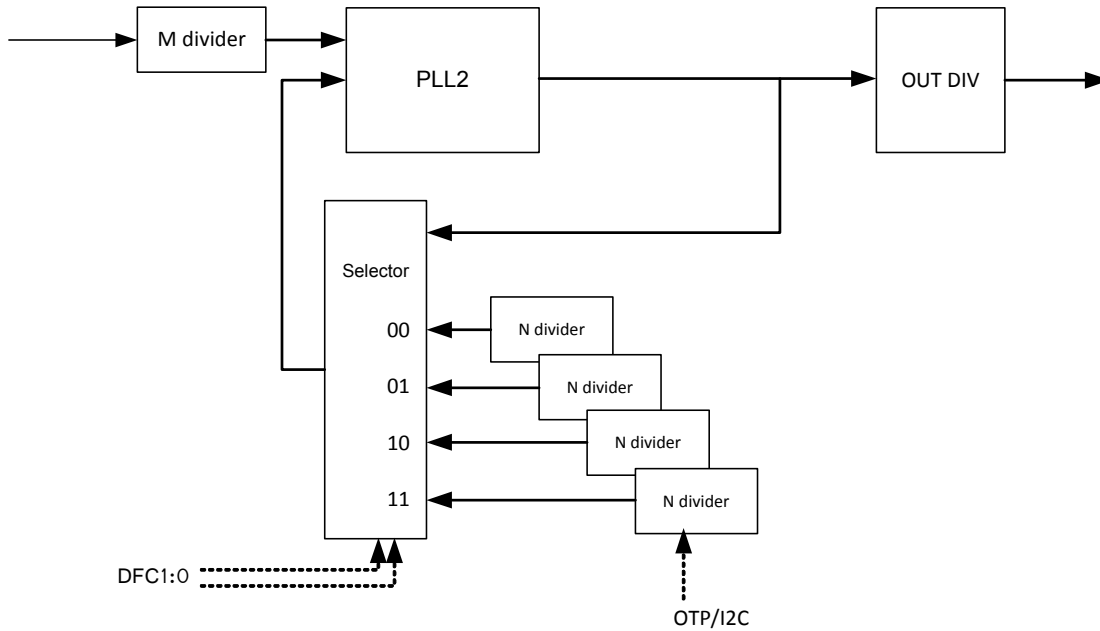
Number	Name	Type	Description
1	VDDA	Power	VDD 3.3V.
2	SDA_DFC0	I/O	I2C DATA pin, can be setup become DFC0 by OTP programming.
3	SEL_DFC/SCL_DFC1	Input	I2C CLK pin, SEL_DFC is a latch input pin during the power up High on power on: I2C mode as SCLK function, Low on power on: SCL and SDA as DFC function pins.
4	CLKIN/X2	I/O	Crystal oscillator interface output or differential clock input pin (CLKIN).
5	CLKINB/X1	Input	Crystal oscillator interface input or differential clock input pin (CLKINB).
6	VBAT	Power	Power supply pin for 32.768kHz DCO, usually connect to coin cell battery, 2.5-3.3V.
7	VSS	Power	Connect to ground.
8	VDD33	Power	VDD 3.3V.
9	VSSSE1	Power	Connect to ground.
10	VDDSE1	Power	Output power supply. Connect to 1.8 to 3.3V. Sets output voltage levels for SE1.
11	SE1	Output	Output Clock SE1.
12	OE1	Input	OE1's function selected from OTP preprogram register bits. OE1 pull-up to 6.5V when burn OTP registers. Refer to OE function table for details.
13	VDDDIFF1	Power	Output power supply. Connect to 2.5 to 3.3V. Sets output voltage levels for DIFF1.
14	DIFF1B	Output	Differential clock output 1_Complement, can be OTP pre-program to LVCMOS/LPHCSL/LVDS/LVPECL output type.
15	DIFF1	Output	Differential clock output 1_True, can be OTP pre-program to LVCMOS/LPHCSL/LVDS/LVPECL output type.
16	VSSDIFF1	Power	Connect to ground.
17	VDDDIFF2	Power	Output power supply. Connect to 2.5 to 3.3V. Sets output voltage levels for DIFF2.
18	DIFF2B	Output	Differential clock output 2_Complement, can be OTP pre-program to LVCMOS/LPHCSL/LVDS/LVPECL output type.
19	DIFF2	Output	Differential clock output 2_True, can be OTP pre-program to LVCMOS/LPHCSL/LVDS/LVPECL output type.
20	VSSDIFF2	Power	Connect to ground.
21	EPAD	Power	Connect to ground.

Device Feature and Function

DFC–Dynamic Frequency Control

- OTP program (Only) setup 4 different feedback fractional divider (4 VCO frequencies) that apply to PLL2
- ORT (overshoot reduction) function will be applied automatically during the VCO frequency change
- Smooth frequency incremental or decremental from current VCO to targeted VCO base on DFC hardware pins selection

DFC Block Diagram



DFC Function Priority Table

DFC_EN bit(W32[4])	OE1_fun_sel (W30[6:5])	*OE3_fun_sel (W30[3:2])	SCL_DFC1	DFC[1:0]	Notes
0	x	x	x	0	DFC disable
1	11 (DFC)	00-10 (DFC)	x	[0,OE1]	One pin DFC - OE1
1	11 (DFC)	11 (DFC)	x	[OE3,OE1]	Two pin DFC - OE3,OE1
1	00-10	11	x	Not permit	Not supported
1	00-10	00-10	0	[SCL_DFC1, SDA_DFC0]	I2C pin as DFC control pins mode
1	00-10	00-10	1	W30[1:0]	I2C control DFC mode

* 5P35021 has only OE1 pin for DFC function hardware pin selection. For OE1/OE3 two pins DFC control, use 5P35023 24-QFN package device.

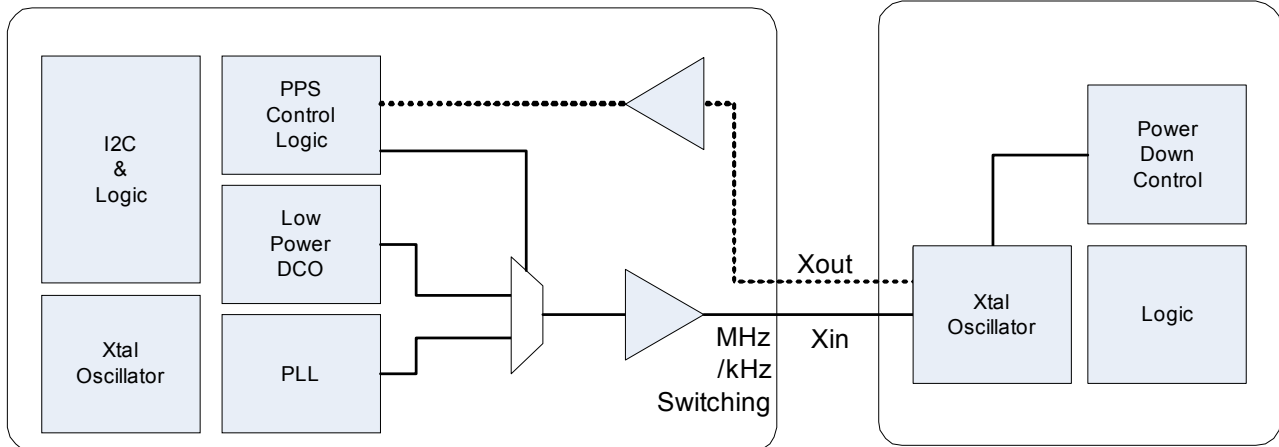
DFC Function Programming

- Register B63b3:2 select DFC00–DFC11 configuration.
- Byte16–19 are the register for PLL2 VCO setting, base on B63b3:2 configuration selection, the data write to B16–19 will be store in selected configuration OTP memory.
- Refer to DFC function priority table, select proper control pin(s) to activate DFC function.
- Note the DFC function can also be controlled by I²C access.

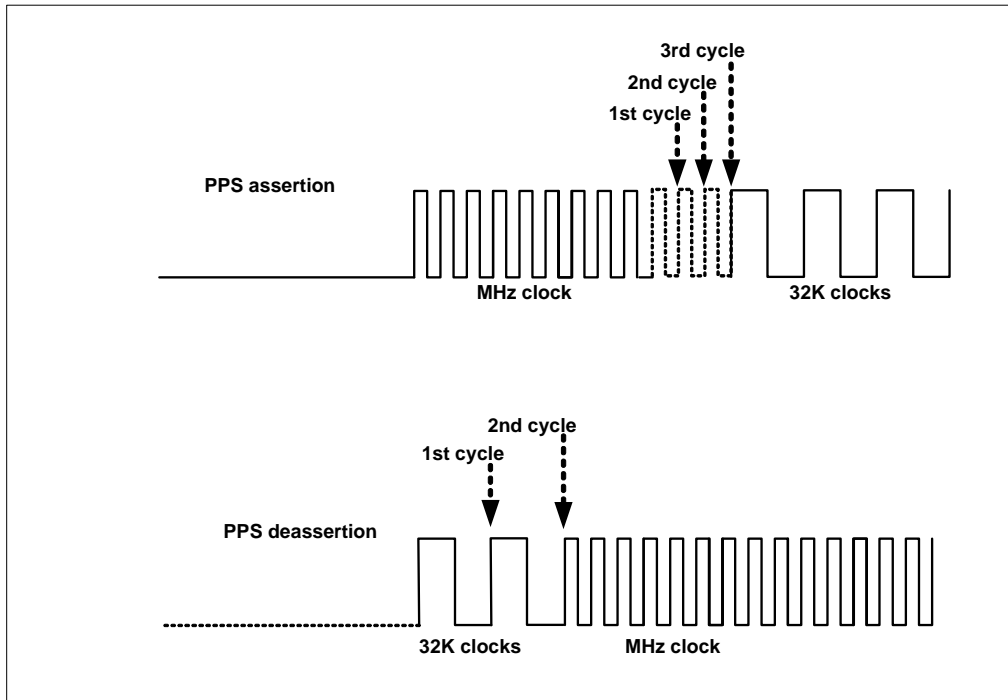
PPS–Proactive Power Saving Function

PPS Proactive Power Saving is an IDT patented unique design for the clock generator that proactively detects end device power down state and then switches output clocks between the normal operation clock frequency and the low power mode 32kHz clock that only consume $< 2\mu\text{A}$ current. The system could save power when the device goes into power down or sleep mode. The PPS function diagram is shown below.

PPS Function Block Diagram



PPS Assertion/Deassertion Timing Chart

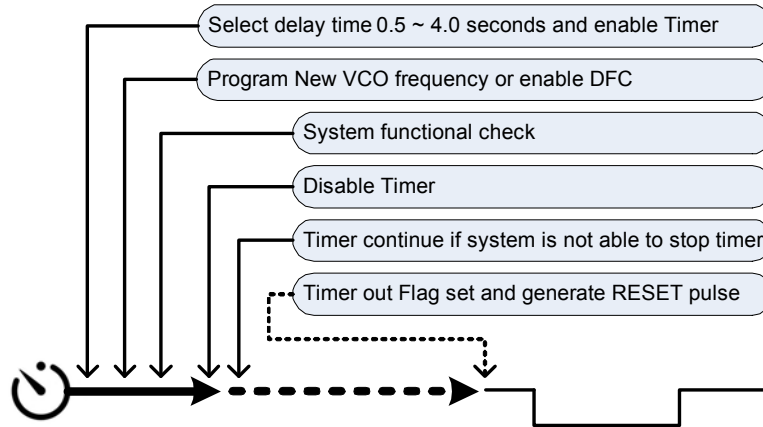


PPS Function Programming

- Refer to OE_pin_function_table to have proper PPS function selected for OE pin(s), please note that register default is set to Output enable (OE).
- Have proper setup to Byte 30 and 32 for OE1~OE3 function selection, for PPS function, select 10 to control register bits.

Timer Function Description

1. The timer function can be used together with the DFC (Dynamic Frequency Control) function or with another PLL frequency programming.
2. The timer provides 4 different delay times by two bits selection: 0.5 seconds, 1 seconds, 2 seconds, 4 seconds.
3. The timeout flag will be set when timer times out, and the flag can be cleared by writing 0 to timer enable bit.
4. When timer times out, RESET pin (available in 5P35023) can generate a 250ms pulse signal if RESET control bit is enabled.
5. When timer times out, DFC stage will switch back to DFC00 setting if DFC function is enabled and DFC function will be disabled after RESET.



OE Pin Function

OE pins in the 5P35021 have multiple functions. The OE pins can be configured as output enable control (OE) or chip power down control (PD#) or Proactive Power Saving function (PPS). Furthermore, the OE pins can be configured as single or two pin dynamic Frequency control (DFC), or the RESET out function that is associated with the Timer function.

OE Pin Function Table

Function	Pin		
	OE1	OE2 (Not available in 5P35021)	OE3 (Not available in 5P35021)
SE Output Enable/Disable	SE1 (Default)	SE2 (Default)	SE3 (Default)
DIFF Output Enable/Disable	-	DIFF1/DIFF2	-
Global Power Down (PD#)	PD#	-	-
Proactive Power Saving Input	SE1_PPS	SE2_PPS	SE3_PPS
DOC Control (Only PLL2)	DFC0	-	DFC1
RESET OUT	-	RESET OUT	-

OE Pin Function Summary (* Note: OE2, OE3 and SE2, SE3 pins are only available in 5P35023)

OE1: SE1	OE1 only control SE1 enable/disable, other outputs are not affected by this pin status
* OE2: SE2	OE2 only control SE2 enable/disable, other outputs are not affected by this pin status
* OE2: SE3	OE3 only control SE3 enable/disable, other outputs are not affected by this pin status
* OE2: DIFF1/DIFF2	OE2 control Differential outputs 1 and 2 only, other SE outputs are not affected by this pin status
OE1: PD#	OE1 control chip global power down (PD#) except 32.768KHz on OE1 (when 32K is enabled),
OE1: SE1_PPS	Config OE1 as SE1_PPS (Proactive Power Saving) function pin
* OE1: SE2_PPS	Config OE2 as SE2_PPS (Proactive Power Saving) function pin
* OE1: SE3_PPS	Config OE3 as SE3_PPS (Proactive Power Saving) function pin
OE1:DFC0	Config OE1 as DFC0 control pin0
* OE3/DFC1	Config OE3 as DFC1 control pin1

PD# Priority Table

PD#	I2C_OE_EN_bit	SE1, DIFF1/DIFF2 SE1_PPS	Output	Notes
0	x	x	stop	32kHz free run
1	0	x	stop	
1	1	0	stop	
1	1	1	running	

Reference Input and Selection

The 5P35021 accepts crystal input or LVCMOS/Differential clocks input by external AC coupling. See below reference circuit for details.

Crystal Input (X1/X2)

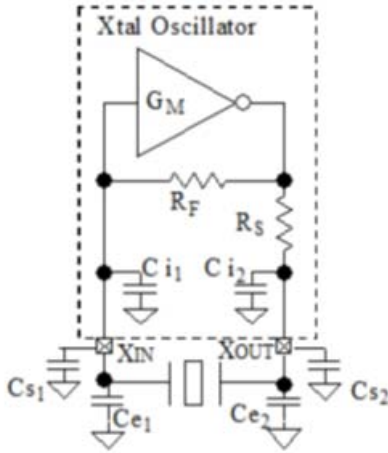
The crystal oscillators should be fundamental mode quartz crystals; overtone crystals are not suitable. Crystal frequency should be specified for parallel resonance with 40MHz maximum.

A crystal manufacturer will calibrate its crystals to the nominal frequency with a certain load capacitance value. When the oscillator load capacitance matches the crystal load capacitance, the oscillation frequency will be accurate as 0 PPM. When the oscillator load capacitance is lower than the crystal load capacitance, the oscillation frequency will be higher than nominal. In order to get an accurate oscillation frequency, the matching the oscillator load capacitance with the crystal load capacitance is required.

To set the oscillator load capacitance, 5P35021 has built-in two programmable tuning capacitors inside the chip, one at XIN and one at XOUT. They can be adjusted independently. The value of each capacitor is composed of a fixed capacitance amount plus a variable capacitance amount set with the XTAL[7:0] register. Adjustment of the crystal tuning capacitors allows for maximum flexibility to accommodate crystals from various manufacturers. The range of tuning capacitor values available are in accordance with the following table.

Programmable Tuning Caps Table

Parameter	Bits	Range	Min (pF)	Max (pF)
Xtal [7:0]	4*2	+1/+2/+4/+8 pF	0	15pF



$$XTAL[4:0] = (XTAL CL - 7pF) \times 2 \quad (\text{Eq.1})$$

Equation 1 and the table of XTAL[7:0] tuning capacitor characteristics show that the parallel tuning capacitance can be set between 4.5pF to 12.5pF with a resolution of 0.25pF.

For a crystal $C_L = 8pF$, where C_L is the parallel capacity specified by the crystal vendor that sets the crystal frequency to the nominal value. Under the assumptions that the stray capacity between the crystal leads on the circuit board is zero and that no external tuning caps are placed on the crystal leads, then the internal parallel tuning capacity is equal to the load capacity presented to the crystal by the device.

The internal load capacitors are true parallel-plate capacitors for ultra-linear performance. Parallel-plate capacitors were chosen to reduce the frequency shift that occurs when non-linear load capacitance interacts with load, bias, supply, and temperature changes. External non-linear crystal load capacitors should not be used for applications that are sensitive to absolute frequency requirements.

Spread Spectrum

The 5P35021 supports spread spectrum clocks from PLL1 and PLL2; the PLL1 built-in with analog spread spectrum and PLL2 has digital spread spectrum.

Analog Spread Spectrum

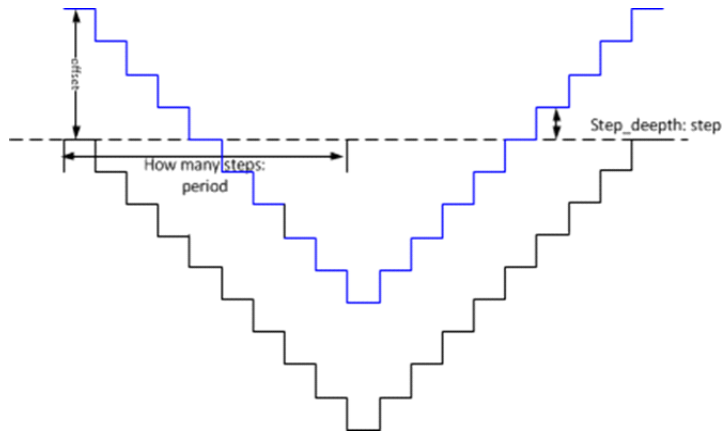
Please refer to programming guide.

Digital Spread Spectrum

$$N = \frac{F_{vco}}{2 * F_{out}}$$

$$period = \frac{F_{pfd}}{2 * F_{ss}}$$

$$step = \frac{N * SS_{amount}}{period}$$



Down spread or Spread off

$$N = F_{vco}/F_{pfd}$$

Center Spread

$$N = N_{soff} + N * SS_{amount}/2$$

N: include integer and fraction

F_{vco}: vco's frequency

F_{pfd}: PLL's pfd frequency

F_{ss}: spread modulation rate

SS_{amount}: spread percentage

The black line is for the down spread, N will decrease to make the center frequency is lower than spread off.

The blue line is for the center spread, there is a offset put on divider ratio to make the center frequency keep same as spread off.

Example: 0.5% down spread at 32kHz modulation rate.

VBAT

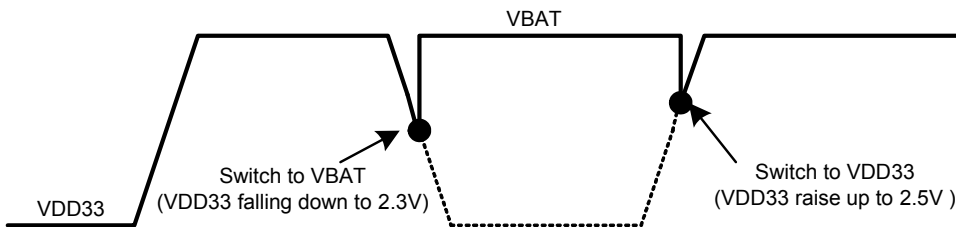
The 5P35021 supports low-power operation 32.768kHz RTC clock with only coin cell battery supply. The coin cell battery power capacitance is usually 170mAh or higher, with less than 2 μ A* low-power DCO operation mode will support application up to few years clock source for date/time keeping circuit (RTC).

When there is main power exist like V_{DD33} and V_{DDA} , the 5P35021 will switch DCO power source to main power to save battery power. V_{BAT} should be powered earlier or at same time with other V_{DD} power up.

VBAT Switching Threshold

VDD33	VBAT	DCO power source
>2.5V	--	VDD33
<2.3V	--	VBAT

*VBAT needs to be 3.0V~3.3V



ORT-VCO Overshoot Reduction Technology

The 5P35021 supports innovate the VCO overshoot reduction technology (ORT) to prevent an output clock frequency spike when the device is changing frequency on the fly or doing DFC (Dynamic Frequency Control) function. The VCO frequency changes are under control instead of free-run to targeted frequency.

PLL Features and Descriptions

Output divider 1 table

Output Divider bits<3:2>

Output Divider bits<1:0>	00	01	10	11
00	1	2	4	8
01	4	8	16	32
10	5	10	20	40
11	6	12	24	48

Output 2,4,5 divider table

Output Divider bits<3:2>

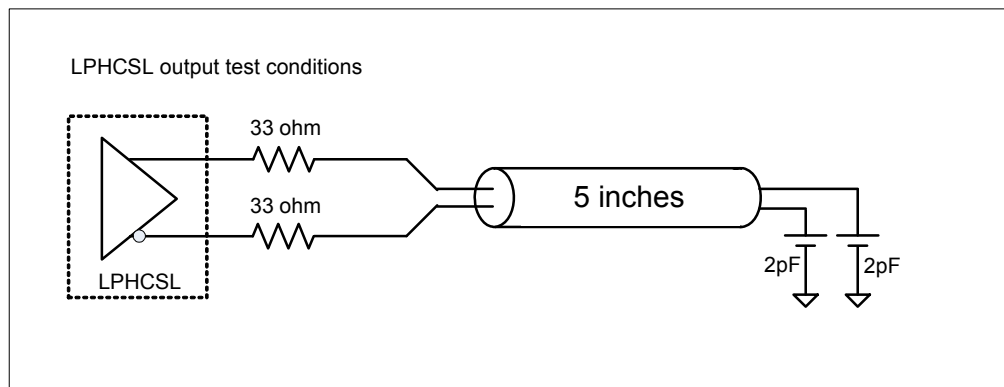
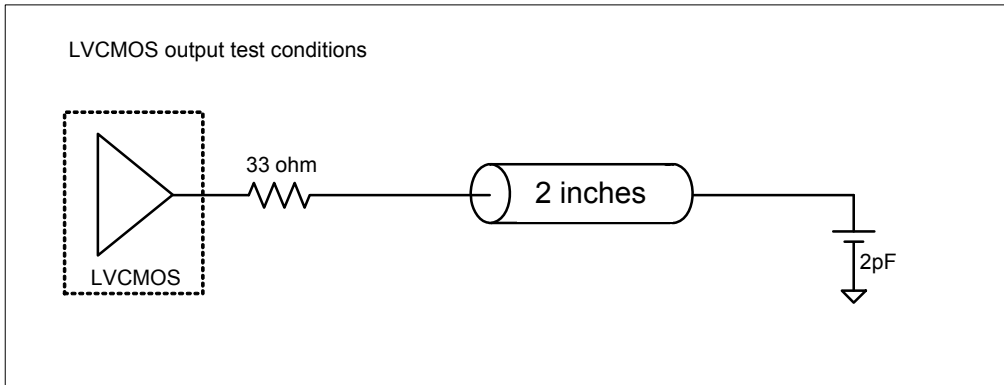
Output Divider bits<1:0>	00	01	10	11
00	1	2	4	5
01	3	6	12	15
10	5	10	20	25
11	10	20	40	50

Output 3 divider table

Output Divider bits<3:2>

Output Divider bits<1:0>	00	01	10	11
00	1	2	4	8
01	3	6	12	24
10	5	10	20	40
11	10	20	40	80

Output Clock Test Conditions



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 5P35021. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDDA, VDD33, VDDSE, VDDDIFF	3.465V
Supply Voltage, VBAT	3.465V
Inputs	
XIN/CLKIN	0V to 3.3V voltage swing for both LVCMOS or DIFF CLK
Other inputs	-0.5V to VDD33/VDDSEx
Outputs, VDDSEx (LVCMOS)	-0.5V to VDDSEx/VDDDIFF+ 0.5V
Outputs, IO (SDA)	10mA
Package Thermal Impedance, Θ_{JA}	42°C/W (0 mps)
Package Thermal Impedance, Θ_{JC}	41.8°C/W (0 mps)
Storage Temperature, TSTG	-65°C to 150°C
ESD Human Body Model,	2500V
ESD Charge Device Model,	1000V
Junction Temperature	125°C

Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
VDDSEx	Power supply voltage for supporting 1.8V outputs	1.71	1.8	1.89	V
	Power supply voltage for supporting 2.5V outputs	2.375	2.5	2.625	V
	Power supply voltage for supporting 3.3V outputs	3.135	3.3	3.465	V
VDD33	Power supply voltage for core logic functions.	3.135	3.3*	3.465	V
VDDA	Analog power supply voltage. Use filtered analog power supply if available.	2.375		3.465	V
VBAT	Battery power supply voltage.	2.8*	3*	3.465	V
	Operating temperature, ambient	-40		85	°C
CLOAD_OUT	Maximum load capacitance (3.3V LVCMOS only)		5		pF
FIN	External reference crystal	8		40	MHz
	External reference crystal with DCO used	12		38	
	External single-ended reference clock CLKINB	1		125	
	External differential reference clock CLKIN, CLKINB	8		125	
tPU	Power up time for all VDDs to reach minimum specified voltage (power ramps must be monotonic),	0.05		3	ms

* Power-up sequence conditions.

* VDDSEx for non-32kHz outputs should be OFF when VDDA/VDD33 turn OFF, VBAT mode only support 32.768kHz outputs from SE1-3.

* **VBAT power ramp up should be same or earlier than other VDD power rail.**

* When use single-ended clock to CLKINB pin within differential clocking mode, CLKIN pin needs to be grounded and minimum input frequency should be higher than 8MHz.

Input Capacitance, LVCMOS Output Impedance, and Internal Pull-down Resistance

(TA = +25 °C)

Symbol	Parameter	Min	Typ	Max	Unit
CIN	Input Capacitance (CLKIN, CLKINB, OE, SDA, SCL, DFC1:0)		3	7	pF
Pull-down Resistor	OE		200		kΩ
ROUT	LVCMOS Output Driver Impedance (VDDSE = 1.8V)		22		
	LVCMOS Output Driver Impedance (VDDSE = 2.5V)		22		
	LVCMOS Output Driver Impedance (VDDSE = 3.3V)		22		Ω
X1, X2	Programmable input capacitance at X1 or X2	0		15	pF

Crystal Characteristics

Parameter	Test Conditions	Min	Typ	Max	Units
Mode of Oscillation		Fundamental			
Frequency		8		40	MHz
Frequency when 32.768K DCO is used		12		38	MHz
Equivalent Series Resistance (ESR)			10	100	Ω
Shunt Capacitance			2	7	pF
Load Capacitance (CL)		6	8	10	pF
Maximum Crystal Drive Level (CL=8pF)				100	μW

DC Electrical Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Iddcore	Core Supply Current	VDD=VDDSE=VDD33=3.3V, Xtal=25MHz, PLL2/3 OFF, No Output - PLLs disabled		5		mA
Idd_PLL1 ³	PLL1 Supply Current	VDD=VDDSE=VDD33=3.3V, Xtal=25MHz, PLL2/3 OFF, No Output - PLL1= 600MHz		13		mA
		VDD=VDDSE=VDD33=2.5V, Xtal=25MHz, PLL2/3 OFF, No Output - PLL1= 600MHz		13		mA
Idd_PLL2 ³	PLL2 Supply Current	VDD=VDDSE=VDD33=3.3V, Xtal=25MHz, PLL1/3 OFF, No Output - PLL2=1GHz		11		mA
		VDD=VDDSE=VDD33=2.5V, Xtal=25MHz, PLL1/3 OFF, No Output - PLL2=1GHz		11		mA
Idd_PLL3 ³	PLL3 Supply Current	VDD=VDDSE=VDD33=3.3V, Xtal=25MHz, PLL1/2 OFF, No Output - PLL3=480MHz		4		mA
Iddox	Output Buffer Supply Current	LVPECL, 500MHz, 3.3V VDDDIFF (DIFF1,2)		39		mA
		LVPECL, 156.25MHz, 2.5V VDDDIFF (DIFF1,2)		33		mA
		LVDS, 500MHz, 3.3V VDDDIFF (DIFF1,2)		13		mA
		LVDS, 250MHz, 2.5V VDDDIFF (DIFF1,2)		8		mA
		LPHCSL, 125MHz, 3.3V VDDDIFF, 2 pF load (DIFF1,2)		7		mA
		LPHCSL, 100MHz, 2.5V VDDDIFF, 2 pF load (DIFF1,2)		8		mA
		LVC MOS, 8MHz, 3.3V, VDDSE ^{1,2} (SE1)		1		mA
		LVC MOS, 8MHz, 2.5V, VDDSE ^{1,2} (SE1)		1		mA
		LVC MOS, 8MHz, 1.8V, VDDSE ^{1,2} (SE1)		1		mA
		LVC MOS, 160MHz, 3.3V VDDSEx1 (SE1)		9.5		mA
		LVC MOS, 160MHz, 2.5V VDDSEx1,2 (SE1)		5.0		mA
LVC MOS, 160MHz, 1.8V VDDSEx1,2 (SE1)		6.0		mA		
Iddpd	Power Down Current	PD asserted with VDDA, VDD33 and VDDSE ON, I2C programming, 32K running		3.5		mA
Iddsuspend - VDD33	Iddsuspend-VBAT	Only VBAT=3.3V and VDDSEn is powered		1.1		µA
Iddsuspend - SE n 3.3V	Iddsuspend - VDDSE n 3.3V	Only VBAT=3.3V and VDDSE n is powered with 3.3V		3.4		µA
Iddsuspend - SE n 2.5V	Iddsuspend - VDDSE n 2.5V	Only VBAT =3.3V and VDDSE n is powered with 2.5V		2.5		µA
Iddsuspend - SE n 1.8V	Iddsuspend - VDDSE n 1.8V	Only VBAT=3.3V and VDDSE n is powered with 1.8V		1.8		µA

1. Single CMOS driver active.

2. SE1-3 current measured with 2 inches transmission line and 2 pF load, DIFF clock current measured with 5 inches transmission line with 2 pF loads.

3. Iddcore = IddA+ IddD, no loads.

Power Consumption of 32.768kHz Output Only Operation

Unless stated otherwise, supply voltage VDDSE = 1.8V–3.3V ±5%, T_A = -40°C to +85°C

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
I_VBAT	Vbat=3.3V power input current			1.1		µA
I_VDDSEx	VDDSEx=1.8V current	0.5 inch, no load, one output		0.4		µA
I_VDDSEx	VDDSEx=1.8V current	2.0 inch, no load, one output		1.0		µA
I_VDDSEx	VDDSEx=1.8V current	5.0 inch, no load, one output		2.3		µA
I_VDDSEx	VDDSEx=2.5V current	0.5 inch, no load, one output		0.6		µA
I_VDDSEx	VDDSEx=2.5V current	2.0 inch, no load, one output		1.5		µA
I_VDDSEx	VDDSEx=2.5V current	5.0 inch, no load, one output		3.1		µA
I_VDDSEx	VDDSEx=3.3V current	0.5 inch, no load, one output		0.8		µA
I_VDDSEx	VDDSEx=3.3V current	2.0 inch, no load, one output		1.9		µA
I_VDDSEx	VDDSEx=3.3V current	5.0 inch, no load, one output		4.2		µA

Electrical Characteristics – Input Parameters ^{1,2}

Unless stated otherwise, supply voltage VDDD33 = 3.3V ±5%, T_A = -40°C to +85°C

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V _{IH}	Input High Voltage - CLKIN	Single-ended input	2.4		3.345	V
V _{IL}	Input Low Voltage - CLKIN	Single-ended input	GND - 0.3		0.8	V
V _{SWING}	Input Amplitude - CLKIN	Differential Input	325		3300	mV
d _w /dt	Input Slew Rate - CLKIN	Differential Input	0.4		8	V/ns
V _{CM}	Input Common Mode Voltage	Differential Input	200mV		2500	mV
I _{IL}	Input Leakage Low Current for OE1	V _{IN} = GND @ OE1 pin	-150		5	µA
I _{IL}	Input Leakage Low Current for OE2/3	V _{IN} = GND			5	µA
I _{IH}	Input Leakage High Current for OE1/2/3	V _{IN} = 3.465			20	µA
d _{TIN}	Input Duty Cycle	Measurement from differential waveform	45		55	%

1. Guaranteed by design and characterization, not 100% tested in production.

2. Slew rate measured through ±75mV window centered around differential zero.

DC Electrical Characteristics for 3.3V LVCMOS

Unless stated otherwise, VDDSE = 3.3V ±5%, T_A = -40°C to +85°C

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V _{OH}	Output HIGH Voltage	I _{OH} = -15mA	2.4		VDDSE	V
V _{OL}	Output LOW Voltage	I _{OL} = 15mA			0.4	V
I _{OZDD}	Output Leakage Current	Tri-state outputs, VDDSE = 3.465V			3	µA
V _{IH}	Input HIGH Voltage	Single-ended inputs - CLKSEL, OE, SDA, SCL	2		VDDSE + 0.3	V
V _{IL}	Input LOW Voltage	Single-ended inputs - CLKSEL, OE, SDA, SCL	GND - 0.3		0.8	V
V _{IH}	Input HIGH Voltage	Single-ended input - XIN/CLKIN	2.4		VDD33	V
V _{IL}	Input LOW Voltage	Single-ended input - XIN/CLKIN	GND - 0.3		0.8	V

DC Electrical Characteristics for 2.5V LVCMOS

Unless stated otherwise, VDDSE = 2.5V ±5%, T_A = -40°C to +85°C

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V _{OH}	Output HIGH Voltage	I _{OH} = -12mA	0.7xVDDSE		VDDSE	V
V _{OL}	Output LOW Voltage	I _{OL} = 12mA			0.4	V
I _{OZDD}	Output Leakage Current	Tri-state outputs, VDDSE = 2.625V			3	µA
V _{IH}	Input HIGH Voltage	Single-ended inputs - CLKSEL, OE, SDA, SCL	1.7		VDDSE + 0.3	V
V _{IL}	Input LOW Voltage	Single-ended inputs - CLKSEL, OE, SDA, SCL	GND - 0.3		0.8	V

DC Electrical Characteristics for 1.8V LVCMOS

Unless stated otherwise, VDDSE = 1.8V ±5%, T_A = -40°C to +85°C

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
VOH	Output HIGH Voltage	IOH = -8mA	0.7 x VDDSE		VDDSE	V
VOL	Output LOW Voltage	IOL = 8mA			0.25 x VDDSE	V
IOZDD	Output Leakage Current	Tri-state outputs, VDDSE = 1.89V			3	µA
VIH	Input HIGH Voltage	Single-ended inputs - OE, SDA, SCL	0.65 * VDDSE		VDDSE + 0.3	V
VIL	Input LOW Voltage	Single-ended inputs - OE, SDA, SCL	GND - 0.3		0.35 * VDDSE	V

Electrical Characteristics–DIF 0.7V LPHCSL Differential Outputs

Unless stated otherwise, VDDDIFF = 3.3 V ±5% or 2.5V ±5%, T_A = -40° to +85°C

Symbol	Parameter	Notes	Min	Typ	Max	Units
dV/dt	Slew Rate	1,2,3,8	1	2.5	4	V/ns
ΔdV/dt	Slew Rate Mismatch	1,2,3,8, at <= 200MHz			20	%
VHIGH	Voltage High	1,6,7,8	660	800	1150	mV
VLOW	Voltage Low	1,6	-150	0	150	mV
VMAX	Maximum Voltage	1			1150	mV
VMIN	Minimum Voltage	1	-300			mV
VSWING	Voltage Swing	1,2,6	300			mV
VCROSS	Crossing Voltage Value	1,4,6	250	360	550	mV
ΔVCROSS	Crossing Voltage variation	1,5			140	mV
Jitter-Cy/Cy	Cycle to Cycle Jitter	1,2		10		ps
Jitter-STJ	Jitter - Period Jitter	1,2		70		ps
Duty Cycle	Duty Cycle	1,2	45		55	%
Measured Frequency	LVHCSL at Differential Output	1,2			500	MHz

* differential clock amplitude setting 00.

Note 1: Guaranteed by design and characterization. Not 100% tested in production.

Note 2: Measured from differential waveform.

Note 3: Slew rate is measured through the VSWING voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

Note 4: VCROSS is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

Note 5: the total variation of all VCROSS measurements in any particular system. Note that this is a subset of VCROSS min/max (VCROSS absolute) allowed. The intent is to limit VCROSS induced modulation by setting ΔVCROSS to be smaller than VCROSS absolute.

Note 6: Measured from single-ended waveform.

Note 7: Measured with scope averaging off, using statistics function. Variation is difference between min. and max.

Note 8: Scope average ON.

DC Electrical Characteristics for LVDS

Unless stated otherwise, $V_{DDIFF} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $T_A = -40^\circ$ to $+85^\circ\text{C}$

Symbol	Parameter	Notes	Min	Typ	Max	Unit
VOT (+)	Differential Output Voltage for the TRUE binary state		247		454	mV
VOT (-)	Differential Output Voltage for the FALSE binary state		-247		-454	mV
Δ VOT	Change in VOT between Complimentary Output States				50	mV
VOS	Output Common Mode Voltage (Offset Voltage)		1.125	1.25	1.375	V
Δ VOS	Change in VOS between Complimentary Output States				50	mV
IOS	Outputs Short Circuit Current, VOUT+ or VOUT- = 0V or VDDIFF			9	24	mA
IOSD	Differential Outputs Short Circuit Current, VOUT+ = VOUT-			6	12	mA
Jitter-Cy/Cy	Cycle to Cycle Jitter	1,2		20		ps
Jitter-STJ	Jitter - ST	1,2		100		ps
Duty Cycle	Duty Cycle	1,2	45		55	%
Measured Frequency	LVDS at Differential Output	1,2			500	MHz

* differential clock amplitude setting 01.

DC Electrical Characteristics for LVPECL

Unless stated otherwise, $V_{DDIFF} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $T_A = -40^\circ$ to $+85^\circ\text{C}$

Symbol	Parameter	Notes	Min	Typ	Max	Unit
VOH	Output Voltage HIGH, terminated through 50 Ω tied to VDDIFF-2 V		VDDIFF - 1.19		VDDIFF - 0.69	V
VOL	Output Voltage LOW, terminated through 50 Ω tied to VDDIFF-2 V		VDDIFF - 1.94		VDDIFF - 1.4	V
VSWING	Peak-to-Peak Output Voltage Swing		0.55		0.993	V
Jitter-Cy/Cy	Cycle to Cycle Litter	1,2		20		ps
Jitter-STJ	Jitter - ST	1,2		100		ps
Duty Cycle	Duty Cycle	1,2	45		55	%
Measured Frequency	LVPECL at Differential Output	1,2			500	MHz

* differential clock amplitude setting 01.

AC Electrical Characteristics

Unless stated otherwise, $V_{DDSE} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$ or $1.8\text{ V} \pm 5\%$, $T_A = -40^\circ$ to $+85^\circ\text{C}$ (spread spectrum OFF)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
fIN 1	Input Frequency	Input frequency limit (XIN)	8		40	MHz
		Input frequency limit (XIN) when enable DCO	12		38	MHz
		Input frequency limit (Differential CLKIN)	8		125	MHz
		Input frequency limit (LVCMOS to X1)	1		125	MHz
fOUT	Output Frequency	Single ended clock output limit (LVCMOS)	1	< 125	160	MHz
		Differential clock output limit (LPHCSL)	1	< 333	500	MHz
		Differential clock output limit (LVDS)	1	< 333	500	MHz
		Differential clock output limit (LVPECL)	1		500	MHz
fVCO1	VCO frequency range of PLL1	VCO operating frequency range	300		600	MHz
fVCO2	VCO frequency range of PLL2	VCO operating frequency range	400		1200	MHz
fVCO3	VCO frequency range of PLL3	VCO operating frequency range	300		800	MHz
t2	Input Duty Cycle	Duty Cycle	45		55	%
t3	Output Duty Cycle	LVCMOS and Differential clock < 333MHz , Crossing point measurements	45		55	%
t3	Output Duty Cycle	LVCMOS and Differential clock > 333MHz , Crossing point measurements	40		60	%
t3	Output Duty Cycle_REF	Reference clock output or SE1-3 fan out clock	40		60	%
t4	Rise/Fall, SLEW[0] = 1	Single-ended LVCMOS output clock rise and fall time, 20% to 80% of VDDSE 1.8V-3.3V		1.0		ns
	Rise/Fall, SLEW[0] = 0	Single-ended LVCMOS output clock rise and fall time, 20% to 80% of VDDSE 1.8V-3.3V		1.1		
t5	Rise Times	LVDS, 20% to 80%		300		ps
	Fall Times	LVDS, 80% to 20%		300		
	Rise Times	LVPECL, 20% to 80%		300		
	Fall Times	LVPECL, 80% to 20%		300		
t6	Clock Jitter	Cycle-to-Cycle jitter (Peak-to-Peak), multiple output frequencies switching, differential outputs (1.8V to 3.3V nominal output voltage) SE1 = 25MHz *SE2 = 100MHz *SE3 = 100MHz DIFF1/2 = 100MHz		50		ps
		RMS Phase Jitter (12kHz to 20MHz integration range) differential output, VDDSE = 3.465V, 25MHz crystal, SE1 = 25MHz *SE2 = 100MHz *SE3 = 100MHz DIFF1/2 = 100MHz		1.1		ps
t7	Output Skew	Skew between the same frequencies, with outputs using the same driver format		75		ps
t8 2	Lock Time	PLL lock time from power-up			20	ms
t9	Lock Time	32.768kHz clock low power power-up time		10	100	ms
t9 3	Lock Time	PLL lock time from shutdown mode		0.1	2	ms

1. Practical lower frequency is determined by loop filter settings.

2. Includes loading the configuration bits from EPROM to PLL registers. It does not include EPROM programming/write time.

3. Actual PLL lock time depends on the loop configuration.

4. * SE2/SE3 are not available in 5P35021, only available in 5P35023 QFN24 device.

5. t4 Rise/Fall time measurements are based on 5pF load.

6. t5 Rise/Fall time measurements are based on 2pF load.

PCI Express Jitter Specifications

Unless stated otherwise, $V_{DDIFF} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$, $T_A = -40^\circ$ to $+85^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Typ	Max	PCIe Industry Specification	Units	Notes
tJ (PCIe Gen1)	Phase Jitter Peak-to-Peak	$f = 100\text{MHz}/125\text{MHz}$, 25MHz Crystal Input Evaluation Band: 0Hz - Nyquist (clock frequency/2)		30		86	ps	1,4
tREFCLK_HF_RMS (PCIe Gen2)	Phase Jitter RMS	$f = 100\text{MHz}/125\text{MHz}$, 25MHz Crystal Input High Band: 1.5MHz - Nyquist (clock frequency/2)		2.56		3.10	ps	2,4
tREFCLK_LF_RMS (PCIe Gen2)	Phase Jitter RMS	$f = 100\text{MHz}/125\text{MHz}$, 25MHz Crystal Input Low Band: 10kHz - 1.5MHz		0.27		3.0	ps	2,4
tREFCLK_RMS (PCIe Gen3)	Phase Jitter RMS	$f = 100\text{MHz}/125\text{MHz}$, 25MHz Crystal Input Evaluation Band: 0Hz - Nyquist (clock frequency/2)		0.8		1.0	ps	3,4

Note: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

1. Peak-to-Peak jitter after applying system transfer function for the Common Clock Architecture. Maximum limit for PCI Express Gen 1.
2. RMS jitter after applying the two evaluation bands to the two transfer functions defined in the Common Clock Architecture and reporting the worst case results for each evaluation band. Maximum limit for PCI Express Generation 2 is 3.1ps RMS for tREFCLK_HF_RMS (High Band) and 3.0ps RMS for tREFCLK_LF_RMS (Low Band).
3. RMS jitter after applying system transfer function for the common clock architecture. This specification is based on the PCI_Express_Base_r3.0 10 Nov, 2010 specification, and is subject to change pending the final release version of the specification.
4. This parameter is guaranteed by characterization. Not tested in production.

Spread Spectrum Generation Specifications

Symbol	Parameter	Description	Min	Typ	Max	Unit
fOUT	Output Frequency	Output Frequency Range	1		350	MHz
fMOD*	Mod Frequency	Modulation Frequency		30 to 63		kHz
fSPREAD	Spread Value	Amount of Spread Value (programmable) - Down Spread		-0.5% to -2%		%fOUT
%tolerance*1	Spread % value	Variation of spread range		+/-15%		%

* input frequency dependent, see programming guide

*1 design target

I2C Bus DC Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VIH	Input HIGH Level		0.7xVDD33			V
VIL	Input LOW Level				0.3xVDD33	V
VHYS	Hysteresis of Inputs		0.05xVDD33			V
IIN	Input Leakage Current				±1	µA
VOL	Output LOW Voltage	IOL = 3 mA			0.4	V

I2C Bus AC Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
FSCLK	Serial Clock Frequency (SCL)		100	400	kHz
tBUF	Bus free time between STOP and START	1.3			µs
tSU:START	Setup Time, START	0.6			µs
tHD:START	Hold Time, START	0.6			µs
tSU:DATA	Setup Time, data input (SDA)	100			ns
tHD:DATA	Hold Time, data input (SDA) 1	0			µs
tOVD	Output data valid from clock			0.9	µs
CB	Capacitive Load for Each Bus Line			400	pF
tR	Rise Time, data and clock (SDA, SCL)	20 + 0.1xCB		300	ns
tF	Fall Time, data and clock (SDA, SCL)	20 + 0.1xCB		300	ns
tHIGH	HIGH Time, clock (SCL)	0.6			µs
tLOW	LOW Time, clock (SCL)	1.3			µs
tSU:STOP	Setup Time, STOP	0.6			µs

Note 1: A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH(MIN) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

General I²C Mode Operations

The device acts as a slave device on the I²C bus using one of the four I²C addresses (0xD0, 0xD2, 0xD4, or 0xD6) to allow multiple devices to be used in the system. The interface accepts byte-oriented block write and block read operations. Two address bytes specify the register address of the byte position of the first register to write or read. Data bytes (registers) are accessed in sequential order from the lowest to the highest byte (most significant bit first). Read and write block transfers can be stopped after any complete byte transfer. During a write operation, data will not be moved into the registers until the STOP bit is received, at which point, all data received in the block write will be written simultaneously.

For full electrical I²C compliance, it is recommended to use external pull-up resistors for SDATA and SCLK. The internal pull-down resistors have a size of 100k Ω typical.

I²C Slave Read and Write Cycle Sequencing

Current Read



Sequential Read



Sequential Write



- from master to slave
- from slave to master

S = start
 Sr = repeated start
 A = acknowledge
 Abar = none acknowledge
 P = stop

Byte0: General Control

Byte 00h	Name	Control Function	Type	0	1	PWD
Bit 7	OTP_Burned	OTP memory programming indication	R/W	OTP memory non-programmed	OTP memory programmed	0
Bit 6	I2C_addr[1]	I2C address select bit 1	R/W	00: D0 / 01: D2		0
Bit 5	I2C_addr[0]	I2C address select bit 0	R/W	10: D4 / 11: D6		0
Bit 4	PLL1_SSEN	PLL1 Spread Spectrum enable	R/W	disable	enable	0
Bit 3	DIV1_src_sel	Divider 1 source clock select	R/W	PLL1	Xtal	0
Bit 2	PLL3_refin_sel	PLL3 source selection	R/W	Xtal	Seed (DIV2)	0
Bit 1	EN_CLKIN	enable CLKIN	R/W	disable	enable	0
Bit 0	OTP_protect	OTP memory protection	R/W	read/write	write locked	0

Byte1: Dash Code ID (optional)

Byte 01h	Name	Control Function	Type	0	1	PWD
Bit 7	DashCode ID[7]	Dash code ID	R/W	-	-	0
Bit 6	DashCode ID[6]	Dash code ID	R/W	-	-	0
Bit 5	DashCode ID[5]	Dash code ID	R/W	-	-	0
Bit 4	DashCode ID[4]	Dash code ID	R/W	-	-	0
Bit 3	DashCode ID[3]	Dash code ID	R/W	-	-	0
Bit 2	DashCode ID[2]	Dash code ID	R/W	-	-	0
Bit 1	DashCode ID[1]	Dash code ID	R/W	-	-	0
Bit 0	DashCode ID[0]	Dash code ID	R/W	-	-	0

Byte2: Crystal Cap setting

Byte 02h	Name	Control Function	Type	0	1	PWD
Bit 7	Xtal_Cap[7]	Xtal cap load trimming bits	R/W	x1 x2 x4 x8 total 15pf		0
Bit 6	Xtal_Cap[6]	Xtal cap load trimming bits	R/W			0
Bit 5	Xtal_Cap[5]	Xtal cap load trimming bits	R/W			0
Bit 4	Xtal_Cap[4]	Xtal cap load trimming bits	R/W			1
Bit 3	Xtal_Cap[3]	Xtal cap load trimming bits	R/W			0
Bit 2	Xtal_Cap[2]	Xtal cap load trimming bits	R/W			0
Bit 1	Xtal_Cap[1]	Xtal cap load trimming bits	R/W			0
Bit 0	Xtal_Cap[0]	Xtal cap load trimming bits	R/W			1

Byte3: PLL3 M Divider

Byte 03h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL3_MDIV1	PLL3 source clock divider	R/W	disable M DIV1	bypadd divider (/1)	0
Bit 6	PLL3_MDIV2	PLL3 source clock divider	R/W	disable M DIV2	bypadd divider (/2)	0
Bit 5	PLL3_M_DIV[5]	PLL3 reference integer divider	R/W	3~64	default 25	0
Bit 4	PLL3_M_DIV[4]	PLL3 reference integer divider	R/W	-	-	1
Bit 3	PLL3_M_DIV[3]	PLL3 reference integer divider	R/W	-	-	1
Bit 2	PLL3_M_DIV[2]	PLL3 reference integer divider	R/W	-	-	0
Bit 1	PLL3_M_DIV[1]	PLL3 reference integer divider	R/W	-	-	0
Bit 0	PLL3_M_DIV[0]	PLL3 reference integer divider	R/W	-	-	1

Byte4: PLL3 N Divider

Byte 04h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL3_N_DIV[7]	PLL3 VCO feedback integer divider bit7	R/W	12~2048, default VCO setting is 480MHz		1
Bit 6	PLL3_N_DIV[6]	PLL3 VCO feedback integer divider bit6	R/W			1
Bit 5	PLL3_N_DIV[5]	PLL3 VCO feedback integer divider bit5	R/W			1
Bit 4	PLL3_N_DIV[4]	PLL3 VCO feedback integer divider bit4	R/W			0
Bit 3	PLL3_N_DIV[3]	PLL3 VCO feedback integer divider bit3	R/W			0
Bit 2	PLL3_N_DIV[2]	PLL3 VCO feedback integer divider bit2	R/W			0
Bit 1	PLL3_N_DIV[1]	PLL3 VCO feedback integer divider bit1	R/W			0
Bit 0	PLL3_N_DIV[0]	PLL3 VCO feedback integer divider bit0	R/W			0

Byte5: PLL3 Loop filter setting and N Divider10:8

Byte 05h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL3_R100K	PLL3 Loop filter resistor 100Kohm	R/W	bypass	plus 100Kohm	0
Bit 6	PLL3_R50K	PLL3 Loop filter resistor 50Kohm	R/W	bypass	plus 50Kohm	0
Bit 5	PLL3_R25K	PLL3 Loop filter resistor 25Kohm	R/W	bypass	plus 25Kohm	0
Bit 4	PLL3_R12.5K	PLL3 Loop filter resistor 12.5Kohm	R/W	bypass	plus 12.5Kohm	1
Bit 3	PLL3_R6K	PLL3 Loop filter resistor 6Kohm	R/W	bypass	only 6Kohm applied	0
Bit 2	PLL3_N_DM[10]	PLL3 VCO feedback integer divider bit10	R/W	12~2048, default VCO setting is 480MHz		0
Bit 1	PLL3_N_DM[9]	PLL3 VCO feedback integer divider bit9	R/W			0
Bit 0	PLL3_N_DM[8]	PLL3 VCO feedback integer divider bit8	R/W			1

Byte6: PLL3 charge pump control

Byte 06h	Name	Control Function	Type	0	1	PWD
Bit 7	OUTDIV3 Source	Output divider 3 source clock selection	R/W	PLL2	PLL3	0
Bit 6	PLL3_CP_8X	PLL3 charge pump control	R/W	-	x8	1
Bit 5	PLL3_CP_4X	PLL3 charge pump control	R/W	-	x4	1
Bit 4	PLL3_CP_2X	PLL3 charge pump control	R/W	-	x2	0
Bit 3	PLL3_CP_1X	PLL3 charge pump control	R/W	-	x1	1
Bit 2	PLL3_CP_/24	PLL3 charge pump control	R/W	-	/24	1
Bit 1	PLL3_CP_/3	PLL3 charge pump control	R/W	-	/3	0
Bit 0	PLL3_SIREF	PLL3 SiRef current selection	R/W	10uA	20uA	0

Notes: Formula : $(iRef (10uA) * (1+SIREF) * (1*1X+2*2X+4*4X+8*8X+16*16X))/((24*/24)+(3*/3))$

Byte7: PLL1 Control and OUTDIV5 divider

Byte 07h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_MDIV_Doubler	PLL1 reference clock doubler	R/W	disable	enable	0
Bit 6	PLL1_SIREF	PLL1 SiRef current selection	R/W	10.8uA	21.6uA	0
Bit 5	PLL1_EN_CH2	PLL1 output Channel 2 control	R/W	disable	enable	1
Bit 4	PLL1_EN_3rdpole	PLL1 3rd Pole control	R/W	disable	enable	0
Bit 3	OUTDIV5[3]	Output divider5 control bit 3	R/W	-	-	0
Bit 2	OUTDIV5[2]	Output divider5 control bit 2	R/W	-	-	0
Bit 1	OUTDIV5[1]	Output divider5 control bit 1	R/W	-	-	1
Bit 0	OUTDIV5[0]	Output divider5 control bit 0	R/W	-	-	1

Byte8: PLL1 M Divider

Byte 08h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_MDIV1	PLL3 VCO referenceclock divider 1	R/W	disable MDIV1	bypass divider (/1)	0
Bit 6	PLL1_MDIV2	PLL3 VCO referenceclock divider 2	R/W	disable MDIV2	bypass divider (/2)	0
Bit 5	PLL1_M_DM[5]	PLL1 reference clock divider control bit 5	R/W	3~64, default is 25		0
Bit 4	PLL1_M_DM[4]	PLL1 reference clock divider control bit 4	R/W			1
Bit 3	PLL1_M_DM[3]	PLL1 reference clock divider control bit 3	R/W			1
Bit 2	PLL1_M_DM[2]	PLL1 reference clock divider control bit 2	R/W			0
Bit 1	PLL1_M_DM[1]	PLL1 reference clock divider control bit 1	R/W			0
Bit 0	PLL1_M_DM[0]	PLL1 reference clock divider control bit 0	R/W			1

Byte9: PLL1 VCO N divider

Byte 09h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_N_DM[7]	PLL1 VCO feedback divider control bit 7	R/W	12~2048, default is 600		0
Bit 6	PLL1_N_DM[6]	PLL1 VCO feedback divider control bit 6	R/W			1
Bit 5	PLL1_N_DM[5]	PLL1 VCO feedback divider control bit 5	R/W			0
Bit 4	PLL1_N_DM[4]	PLL1 VCO feedback divider control bit 4	R/W			1
Bit 3	PLL1_N_DM[3]	PLL1 VCO feedback divider control bit 3	R/W			1
Bit 2	PLL1_N_DM[2]	PLL1 VCO feedback divider control bit 2	R/W			0
Bit 1	PLL1_N_DM[1]	PLL1 VCO feedback divider control bit 1	R/W			0
Bit 0	PLL1_N_DM[0]	PLL1 VCO feedback divider control bit 0	R/W			0

Byte10: PLL loop filter and N divider

Byte 0Ah	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_R100K	PLL1 Loop filter resistor 100Kohm	R/W	bypass	plus 100Kohm	1
Bit 6	PLL1_R50K	PLL1 Loop filter resistor 50Kohm	R/W	bypass	plus 50Kohm	0
Bit 5	PLL1_R25K	PLL1 Loop filter resistor 25Kohm	R/W	bypass	plus 25Kohm	1
Bit 4	PLL1_R12.5K	PLL1 Loop filter resistor 12.5Kohm	R/W	bypass	plus 12.5Kohm	1
Bit 3	PLL1_R1.0K	PLL1 Loop filter resistor 1Kohm	R/W	bypass	only 1.0Kohm applied	0
Bit 2	PLL1_N_DIV[10]	PLL1 VCO feedback integer divider bit10	R/W	'12~2048, default is 600		0
Bit 1	PLL1_N_DIV[9]	PLL1 VCO feedback integer divider bit9	R/W			1
Bit 0	PLL1_N_DIV[8]	PLL1 VCO feedback integer divider bit8	R/W			0

Byte11: PLL1 charge pump

Byte 0Bh	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_CP_32X	PLL1 charge pump control	R/W	-	x32	0
Bit 6	PLL1_CP_16X	PLL1 charge pump control	R/W	-	x16	0
Bit 5	PLL1_CP_8X	PLL1 charge pump control	R/W	-	x8	0
Bit 4	PLL1_CP_4X	PLL1 charge pump control	R/W	-	x4	0
Bit 3	PLL1_CP_2X	PLL1 charge pump control	R/W	-	x2	0
Bit 2	PLL1_CP_1X	PLL1 charge pump control	R/W	-	x1	1
Bit 1	PLL1_CP_/24	PLL1 charge pump control	R/W	-	/24	1
Bit 0	PLL1_CP_/3	PLL1 charge pump control	R/W	-	/3	0

Byte12: PLL1 spread spectrum control

Byte 0Ch	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_SS_REFDIV23	PLL1 Spread Spectrum control- Ref divider 23	R/W	-	-	0
Bit 6	PLL1_SS_REFDM[6]	PLL1 Spread Spectrum control- Ref divider 6	R/W	-	-	0
Bit 5	PLL1_SS_REFDM[5]	PLL1 Spread Spectrum control- Ref divider 5	R/W	-	-	0
Bit 4	PLL1_SS_REFDM[4]	PLL1 Spread Spectrum control- Ref divider 4	R/W	-	-	0
Bit 3	PLL1_SS_REFDM[3]	PLL1 Spread Spectrum control- Ref divider 3	R/W	-	-	0
Bit 2	PLL1_SS_REFDM[2]	PLL1 Spread Spectrum control- Ref divider 2	R/W	-	-	0
Bit 1	PLL1_SS_REFDM[1]	PLL1 Spread Spectrum control- Ref divider 1	R/W	-	-	0
Bit 0	PLL1_SS_REFDM[0]	PLL1 Spread Spectrum control- Ref divider 0	R/W	-	-	0

Byte13: PLL1 spread spectrum control

Byte 0Dh	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_SS_FBDM[7]	PLL1 Spread Spectrum - feedback divider 7	R/W	-	-	0
Bit 6	PLL1_SS_FBDM[6]	PLL1 Spread Spectrum - feedback divider 6	R/W	-	-	0
Bit 5	PLL1_SS_FBDM[5]	PLL1 Spread Spectrum - feedback divider 5	R/W	-	-	0
Bit 4	PLL1_SS_FBDM[4]	PLL1 Spread Spectrum - feedback divider 4	R/W	-	-	0
Bit 3	PLL1_SS_FBDM[3]	PLL1 Spread Spectrum - feedback divider 3	R/W	-	-	0
Bit 2	PLL1_SS_FBDM[2]	PLL1 Spread Spectrum - feedback divider 2	R/W	-	-	0
Bit 1	PLL1_SS_FBDM[1]	PLL1 Spread Spectrum - feedback divider 1	R/W	-	-	0
Bit 0	PLL1_SS_FBDM[0]	PLL1 Spread Spectrum - feedback divider 0	R/W	-	-	0

Byte14: PLL1 Spread spectrum control

Byte 0Eh	Name	Control Function	Type	0	1	PWD
Bit 7	PLL1_SS_FBDM[15]	PLL1 Spread Spectrum - feedback divider 15	R/W	-	-	0
Bit 6	PLL1_SS_FBDM[14]	PLL1 Spread Spectrum - feedback divider 14	R/W	-	-	0
Bit 5	PLL1_SS_FBDM[13]	PLL1 Spread Spectrum - feedback divider 13	R/W	-	-	0
Bit 4	PLL1_SS_FBDM[12]	PLL1 Spread Spectrum - feedback divider 12	R/W	-	-	0
Bit 3	PLL1_SS_FBDM[11]	PLL1 Spread Spectrum - feedback divider 11	R/W	-	-	0
Bit 2	PLL1_SS_FBDM[10]	PLL1 Spread Spectrum - feedback divider 10	R/W	-	-	0
Bit 1	PLL1_SS_FBDM[09]	PLL1 Spread Spectrum - feedback divider 9	R/W	-	-	0
Bit 0	PLL1_SS_FBDM[08]	PLL1 Spread Spectrum - feedback divider 8	R/W	-	-	0

Byte15: Output divider1 control

Byte 0Fh	Name	Control Function	Type	0	1	PWD
Bit 7	OUTDIV1[3]	Output divider1 control bit 3	R/W	-	-	0
Bit 6	OUTDIV1[2]	Output divider1 control bit 2	R/W	-	-	0
Bit 5	OUTDIV1[1]	Output divider1 control bit 1	R/W	-	-	1
Bit 4	OUTDIV1[0]	Output divider1 control bit 0	R/W	-	-	1
Bit 3	OUTDIV2[3]	Output divider2 control bit 3	R/W	-	-	0
Bit 2	OUTDIV2[2]	Output divider2 control bit 2	R/W	-	-	0
Bit 1	OUTDIV2[1]	Output divider2 control bit 1	R/W	-	-	1
Bit 0	OUTDIV2[0]	Output divider2 control bit 0	R/W	-	-	1

Byte16: PLL2 integer feedback divider

Byte 10h	Name	Control Function	Type	0	1	PWD
Bit 7	reserved	-	R/W	-	-	0
Bit 6	reserved	-	R/W	-	-	0
Bit 5	reserved	-	R/W	-	-	0
Bit 4	reserved	-	R/W	-	-	0
Bit 3	reserved	-	R/W	-	-	0
Bit 2	PLL2_FB_INT[10]	PLL2 feedback integer divider 10	R/W	-	-	0
Bit 1	PLL2_FB_INT[9]	PLL2 feedback integer divider 9	R/W	-	-	0
Bit 0	PLL2_FB_INT[8]	PLL2 feedback integer divider 8	R/W	-	-	0

Byte17: PLL2 integer feedback divider

Byte 11h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_FB_INT_DM[7]	PLL2 feedback integer divider 7	R/W	-	-	0
Bit 6	PLL2_FB_INT_DM[6]	PLL2 feedback integer divider 6	R/W	-	-	0
Bit 5	PLL2_FB_INT_DM[5]	PLL2 feedback integer divider 5	R/W	-	-	1
Bit 4	PLL2_FB_INT_DM[4]	PLL2 feedback integer divider 4	R/W	-	-	0
Bit 3	PLL2_FB_INT_DM[3]	PLL2 feedback integer divider 3	R/W	-	-	1
Bit 2	PLL2_FB_INT_DM[2]	PLL2 feedback integer divider 2	R/W	-	-	0
Bit 1	PLL2_FB_INT_DM[1]	PLL2 feedback integer divider 1	R/W	-	-	0
Bit 0	PLL2_FB_INT_DM[0]	PLL2 feedback integer divider 0	R/W	-	-	0

Byte18: PLL2 fractional feedback divider

Byte 12h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_FB_FRC_DM[7]	PLL2 feedback fractional divider 7	R/W	-	-	0
Bit 6	PLL2_FB_FRC_DM[6]	PLL2 feedback fractional divider 6	R/W	-	-	0
Bit 5	PLL2_FB_FRC_DM[5]	PLL2 feedback fractional divider 5	R/W	-	-	0
Bit 4	PLL2_FB_FRC_DM[4]	PLL2 feedback fractional divider 4	R/W	-	-	0
Bit 3	PLL2_FB_FRC_DM[3]	PLL2 feedback fractional divider 3	R/W	-	-	0
Bit 2	PLL2_FB_FRC_DM[2]	PLL2 feedback fractional divider 2	R/W	-	-	0
Bit 1	PLL2_FB_FRC_DM[1]	PLL2 feedback fractional divider 1	R/W	-	-	0
Bit 0	PLL2_FB_FRC_DM[0]	PLL2 feedback fractional divider 0	R/W	-	-	0

Byte19: PLL2 fractional feedback divider

Byte 13h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_FB_FRC_DM[15]	PLL2 feedback fractional divider 15	R/W	-	-	0
Bit 6	PLL2_FB_FRC_DM[14]	PLL2 feedback fractional divider 14	R/W	-	-	0
Bit 5	PLL2_FB_FRC_DM[13]	PLL2 feedback fractional divider 13	R/W	-	-	0
Bit 4	PLL2_FB_FRC_DM[12]	PLL2 feedback fractional divider 12	R/W	-	-	0
Bit 3	PLL2_FB_FRC_DM[11]	PLL2 feedback fractional divider 11	R/W	-	-	0
Bit 2	PLL2_FB_FRC_DM[10]	PLL2 feedback fractional divider 10	R/W	-	-	0
Bit 1	PLL2_FB_FRC_DM[9]	PLL2 feedback fractional divider 9	R/W	-	-	0
Bit 0	PLL2_FB_FRC_DM[8]	PLL2 feedback fractional divider 8	R/W	-	-	0

Byte20: PLL2 spread spectrum control

Byte 14h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_STEP[7]	PLL2 spread step size control bit 7	R/W	-	-	0
Bit 6	PLL2_STEP[6]	PLL2 spread step size control bit 6	R/W	-	-	0
Bit 5	PLL2_STEP[5]	PLL2 spread step size control bit 5	R/W	-	-	0
Bit 4	PLL2_STEP[4]	PLL2 spread step size control bit 4	R/W	-	-	0
Bit 3	PLL2_STEP[3]	PLL2 spread step size control bit 3	R/W	-	-	0
Bit 2	PLL2_STEP[2]	PLL2 spread step size control bit 2	R/W	-	-	0
Bit 1	PLL2_STEP[1]	PLL2 spread step size control bit 1	R/W	-	-	0
Bit 0	PLL2_STEP[0]	PLL2 spread step size control bit 0	R/W	-	-	0

Byte21: PLL2 spread spectrum control

Byte 15h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_STEP[15]	PLL2 spread step size control bit 15	R/W	-	-	0
Bit 6	PLL2_STEP[14]	PLL2 spread step size control bit 14	R/W	-	-	0
Bit 5	PLL2_STEP[13]	PLL2 spread step size control bit 13	R/W	-	-	0
Bit 4	PLL2_STEP[12]	PLL2 spread step size control bit 12	R/W	-	-	0
Bit 3	PLL2_STEP[11]	PLL2 spread step size control bit 11	R/W	-	-	0
Bit 2	PLL2_STEP[10]	PLL2 spread step size control bit 10	R/W	-	-	0
Bit 1	PLL2_STEP[9]	PLL2 spread step size control bit 9	R/W	-	-	0
Bit 0	PLL2_STEP[8]	PLL2 spread step size control bit 8	R/W	-	-	0

Byte22: PLL2 spread spectrum control

Byte 16h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_STEP_DELTA[7]	PLL2 spread step size control delta bit 7	R/W	-	-	0
Bit 6	PLL2_STEP_DELTA[6]	PLL2 spread step size control delta bit 6	R/W	-	-	0
Bit 5	PLL2_STEP_DELTA[5]	PLL2 spread step size control delta bit 5	R/W	-	-	0
Bit 4	PLL2_STEP_DELTA[4]	PLL2 spread step size control delta bit 4	R/W	-	-	0
Bit 3	PLL2_STEP_DELTA[3]	PLL2 spread step size control delta bit 3	R/W	-	-	0
Bit 2	PLL2_STEP_DELTA[2]	PLL2 spread step size control delta bit 2	R/W	-	-	0
Bit 1	PLL2_STEP_DELTA[1]	PLL2 spread step size control delta bit 1	R/W	-	-	0
Bit 0	PLL2_STEP_DELTA[0]	PLL2 spread step size control delta bit 0	R/W	-	-	0

Byte23: PLL2 period control

Byte 17h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_PERIOD[7]	PLL2 period control bit 7	R/W	-	-	0
Bit 6	PLL2_PERIOD[6]	PLL2 period control bit 6	R/W	-	-	0
Bit 5	PLL2_PERIOD[5]	PLL2 period control bit 5	R/W	-	-	0
Bit 4	PLL2_PERIOD[4]	PLL2 period control bit 4	R/W	-	-	0
Bit 3	PLL2_PERIOD[3]	PLL2 period control bit 3	R/W	-	-	0
Bit 2	PLL2_PERIOD[2]	PLL2 period control bit 2	R/W	-	-	0
Bit 1	PLL2_PERIOD[1]	PLL2 period control bit 1	R/W	-	-	0
Bit 0	PLL2_PERIOD[0]	PLL2 period control bit 0	R/W	-	-	0

Byte24: PLL2 control register

Byte 18h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_PERIOD[9]	PLL2 period control bit 9	R/W	-	-	0
Bit 6	PLL2_PERIOD[8]	PLL2 period control bit 8	R/W	-	-	0
Bit 5	PLL2_SSEN	PLL2 spread spectrum enable	R/W	disable	enable	0
Bit 4	PLL2_R100K	PLL2 Loop filter resistor 100Kohm		bypass	plus 100Kohm	0
Bit 3	PLL2_R50K	PLL2 Loop filter resistor 50Kohm		bypass	plus 50Kohm	0
Bit 2	PLL2_R25K	PLL2 Loop filter resistor 25Kohm		bypass	plus 25Kohm	0
Bit 1	PLL2_R12.5K	PLL2 Loop filter resistor 12.5Kohm		bypass	plus 12.5Kohm	0
Bit 0	PLL2_R6K	PLL2 Loop filter resistor 6Kohm		bypass	only 6Kohm applied	0

Byte25: PLL2 charge pump control

Byte 19h	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_CP_16X	PLL2 charge pump control	R/W	-	x16	0
Bit 6	PLL2_CP_8X	PLL2 charge pump control	R/W	-	x8	0
Bit 5	PLL2_CP_4X	PLL2 charge pump control	R/W	-	x4	1
Bit 4	PLL2_CP_2X	PLL2 charge pump control	R/W	-	x2	0
Bit 3	PLL2_CP_1X	PLL2 charge pump control	R/W	-	x1	0
Bit 2	PLL2_CP_/24	PLL2 charge pump control	R/W	-	/24	1
Bit 1	PLL2_CP_/3	PLL2 charge pump control	R/W	-	/3	0
Bit 0	PLL2_SIREF	PLL2 SiRef current selection	R/W	10uA	20uA	0

Byte26: PLL2 M divider setting

Byte 1Ah	Name	Control Function	Type	0	1	PWD	
Bit 7	PLL2_MDIV_Doubler	PLL2 reference divider - doubler	R/W	disable	enable	0	
Bit 6	PLL2_MDIV1	PLL2 reference divider 1	R/W	disable M DIV1	bypadd divider (/1)	1	
Bit 5	PLL2_MDIV2	PLL2 reference divider 2	R/W	disable M DIV2	bypadd divider (/2)	0	
Bit 4	PLL2_MDIV[4]	PLL2 reference divider control bit 4	R/W	3~64, default is 25			0
Bit 3	PLL2_MDIV[3]	PLL2 reference divider control bit 3	R/W				0
Bit 2	PLL2_MDIV[2]	PLL2 reference divider control bit 2	R/W				0
Bit 1	PLL2_MDIV[1]	PLL2 reference divider control bit 1	R/W				0
Bit 0	PLL2_MDIV[0]	PLL2 reference divider control bit 0	R/W				0

Byte27: Output divider 4

Byte 1Bh	Name	Control Function	Type	0	1	PWD
Bit 7	OUTDIV3[3]	Out divider 3 control bit 7	R/W	-	-	0
Bit 6	OUTDIV3[2]	Out divider 3 control bit 6	R/W	-	-	0
Bit 5	OUTDIV3[1]	Out divider 3 control bit 5	R/W	-	-	1
Bit 4	OUTDIV3[0]	Out divider 3 control bit 4	R/W	-	-	1
Bit 3	OUTDIV4[3]	Out divider 4 control bit 3	R/W	-	-	0
Bit 2	OUTDIV4[2]	Out divider 4 control bit 2	R/W	-	-	0
Bit 1	OUTDIV4[1]	Out divider 4 control bit 1	R/W	-	-	1
Bit 0	OUTDIV4[0]	Out divider 4 control bit 0	R/W	-	-	1

Byte28: PLL operation control register

Byte 1Ch	Name	Control Function	Type	0	1	PWD
Bit 7	PLL2_HRS_EN	PLL2 spread high resolution selection enable	R/W	normal	enable (shift 4 bits)	0
Bit 6	PLL2_refin_sel	PLL2 reference clock source select	R/W	Xtal	DIV2	0
Bit 5	PLL3_PDB	PLL3 Power Down	R/W	Power Down	running	1
Bit 4	PLL3_LCKBYPSSB	PLL3 lock bypass	R/W	bypass lock	lock	1
Bit 3	PLL2_PDB	PLL2 Power Down	R/W	Power Down	running	1
Bit 2	PLL2_LCKBYPSSB	PLL2 lock bypass	R/W	bypass lock	lock	1
Bit 1	PLL1_PDB	PLL1 Power Down	R/W	Power Down	running	1
Bit 0	PLL1_LCKBYPSSB	PLL1 lock bypass	R/W	bypass lock	lock	1

Byte29: Output control

Byte 1Dh	Name	Control Function	Type	0	1	PWD	
Bit 7	DIFF1_SEL	Differential clock 1 output OE2 control		not controlled	controlled	0	
Bit 6	DIFF2_SEL	Differential clock 2 output OE2 control		not controlled	controlled	0	
Bit 5	DIFF1_EN	Differential clock 1 output enable	R/W	disable	enable	1	
Bit 4	DIFF2_EN	Differential clock 2 output enable	R/W	disable	enable	1	
Bit 3	OUTDIV4_Source	Output divider 4 source clock selection	R/W	PLL2	Xtal	0	
Bit 2	SE1_SLEW	SE 1 slew rate control	R/W	normal	strong	0	
Bit 1	VDD1_SEL[1]	VDD1 level control bit 1	R/W	00/01: 3.3V 10: 2.5V 11: 1.8			0
Bit 0	VDD1_SEL[0]	VDD1 level control bit 0	R/W				0

Byte30: OE and DFC control

Byte 1Eh	Name	Control Function	Type	0	1	PWD
Bit 7	SE1_EN	SE1 output enable control	R/W	disable	enable	1
Bit 6	OE1_fun_sel[1]	OE1 pin function selection bit 1	R/W	11:DFC0 10: SE1_PPS		0
Bit 5	OE1_fun_sel[0]	OE1 pin function selection bit 0	R/W	01: PD#	00: SE1 OE	0
Bit 4	* SE3_EN	SE3 output enable	R/W	disable	enable	1
Bit 3	* OE3_fun_sel[1]	OE3 pin function selection bit 1	R/W	11: DFC1 10: SE3_PPS		0
Bit 2	* OE3_fun_sel[0]	OE3 pin function selection bit 0	R/W	01:xx	00:SE3_OE	0
Bit 1	* DFC_SW_Sel[1]	DFC frequency select bit 1	R/W	00: N0 01: N1 10:N2 11:N3		0
Bit 0	* DFC_SW_Sel[0]	DFC frequency select bit 0	R/W			0

Byte31: Control Register

Byte 1Fh	Name	Control Function	Type	0	1	PWD
Bit 7	* SE2_Freerun_32K	SE2 32K free run		freerun 32K	B31 bit6 control source	1
Bit 6	* SE2_CLKSEL1	SE2 source clock selection		DIV5	DIV4	0
Bit 5	* VDD2_SEL[1]	VDD2 level control bit 1	R/W	00/01: 3.3V 10: 2.5V 11: 1.8		0
Bit 4	* VDD2_SEL[0]	VDD2 level control bit 0	R/W			0
Bit 3	* SE2_SLEW	SE 2 slew rate control	R/W	normal	strong	0
Bit 2	PLL2_3rd_EN_CFG	PLL2 3rd order control		1st order	3rd order	1
Bit 1	PLL2_EN_CH2	PLL2 channel 2 enable control	R/W	disable	enable	0
Bit 0	PLL2_EN_3rdpole	PLL2 3rd Pole control	R/W	disable	enable	1

Byte32: Control Register

Byte 20h	Name	Control Function	Type	0	1	PWD
Bit 7	* SE2_EN	SE2 output enable	R/W	disable	enable	1
Bit 6	* OE2_fun_sel[1]	OE2 pin function selection bit 1	R/W	11: RESET 10: SE2_PPS		0
Bit 5	* OE2_fun_sel[0]	OE2 pin function selection bit 0	R/W	01: DIFF1/2 OE	00: SE2 OE	0
Bit 4	DFC_EN	DFC function control	R/W	disable	enable	0
Bit 3	WD_EN	WatchDog timer control	R/W	disable	enable	0
Bit 2	Timer_sel<1>	Watchdog timer select bit 1	R/W	00: 250mS 01: 500ms		0
Bit 1	Timer_sel<0>	Watchdog timer select bit 0	R/W	10: 2S	11: 4S	0
Bit 0	Alarm_Flag	Alarm Status(Read Only)	R	No alarm	Alarmed	0

Byte33: SE3 and DIFF1 Control Register

Byte 21h	Name	Control Function	Type	0	1	PWD
Bit 7	* SE3_Freerun_32K	SE3 32K free run	R/W	freerun 32K	DIV2 or DIV4 selected by B33bit6	1
Bit 6	* SE3_CLKSEL1	SE3 source clock selection	R/W	DIV2	DIV4	0
Bit 5	* VDD3_SEL[1]	VDD3 level control bit 1	R/W	11: 1.8V 10: 2.5V		0
Bit 4	* VDD3_SEL[0]	VDD3 level control bit 0	R/W	0x: 3.3V		0
Bit 3	* SE3_SLEW	SE 3 slew rate control	R/W	normal	strong	0
Bit 2	DIFF_PDBHiZEN	Differential output high-Z at power down	R/W	TBD	output tri-state, bias off	0
Bit 1	DIFF1_CMOS2_FLIP	Differential 1/2 LVCMOS output control	R/W	DIFF1_B inverted	DIFF1_B non-inverted	0
Bit 0	DIFF2_CMOS2_FLIP	Differential 1/2 LVCMOS output control	R/W	DIFF2_B inverted	DIFF2_B non-inverted	0

Byte34: DIFF1 Control Register

Byte 22h	Name	Control Function	Type	0	1	PWD
Bit 7	DIFF1_CLK_SEL	Differential clock 1 source selection	R/W	DIV1	DIV3	1
Bit 6	DIFF1_io_pwr_sel	Differential clock 1 output power	R/W	2.5V	3.3V	1
Bit 5	DIFF1_OUTPUT_TYPE[1]	Differential clock 1 type select bit 1	R/W	00: LVMOS 01: LVDS 10: LVPECL 11: LPHCSL		1
Bit 4	DIFF1_OUTPUT_TYPE[0]	Differential clock 1 type select bit 0	R/W			1
Bit 3	DIFF1_AMP[1]	Differential clock 1 amplitude control bit 1	R/W	LPHCSL: 00=740mV,01=800mV,10=855mV,11=910mV LPECL:00=710mV,01=810mV,10=875mV,11=920mV LVDS:00=311mV,01=344mV,10=376mV,11=408mV		0
Bit 2	DIFF1_AMP[0]	Differential clock 1 amplitude control bit 0	R/W			1
Bit 1	DIFF1_CMOS_SLEW	Differential clock 1 LVCMOS slew rate control	R/W	normal	strong	0
Bit 0	D1FF1_CMOS2_EN	Differential clock 1 LVCMOS output_B control	R/W	disable	enable	0

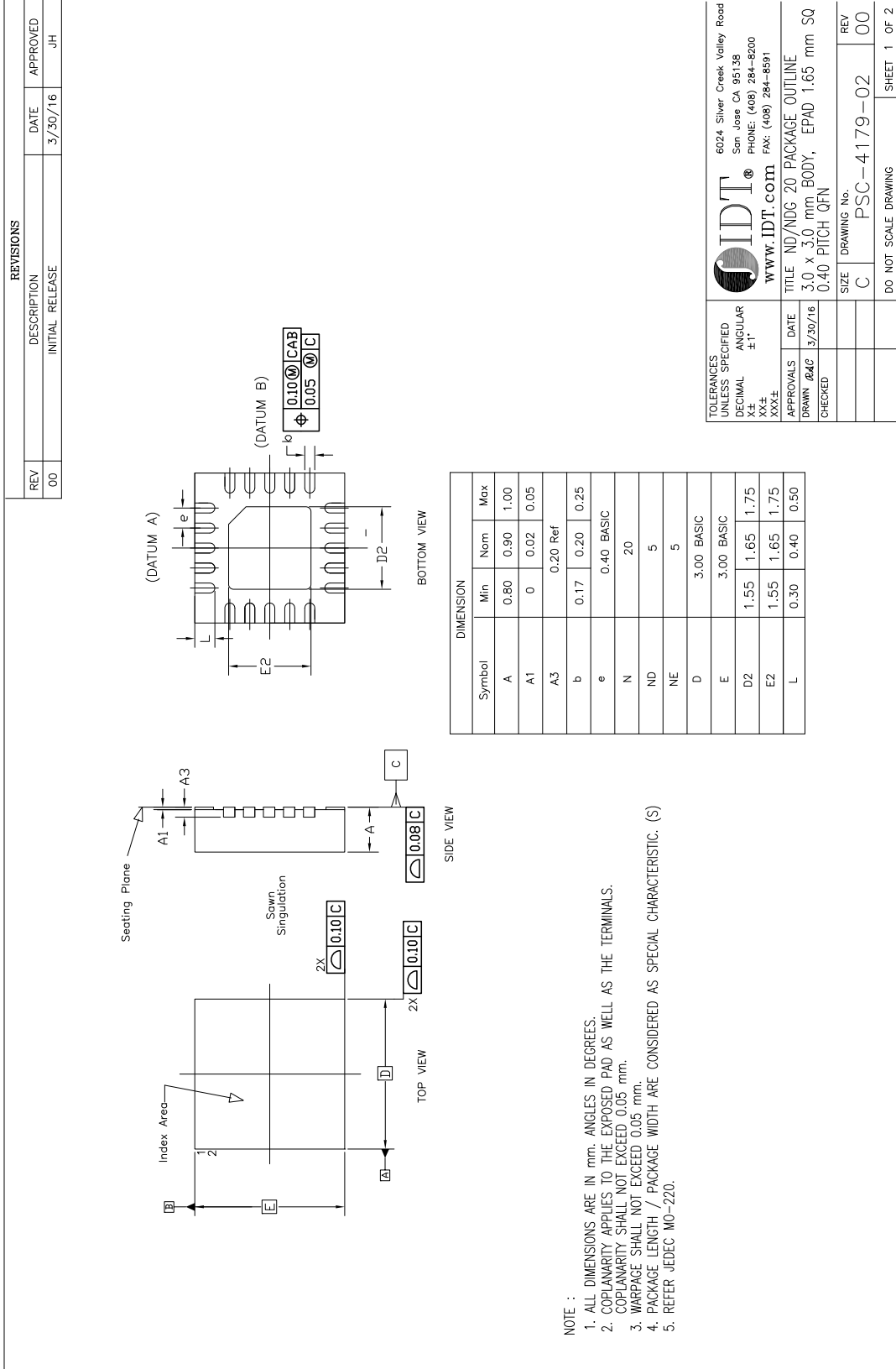
Byte35: DIFF2 Control Register

Byte 23h	Name	Control Function	Type	0	1	PWD
Bit 7	DIFF2_CLK_SEL	Differential clock 2 source selection	R/W	DIV1	DIV3	0
Bit 6	DIFF2_IO_PWR_SEL	Differential clock 2 output power	R/W	2.5V	3.3V	1
Bit 5	DIFF2_OUTPUT_TYPE[1]	Differential clock 2 type select bit 1	R/W	00: LVCMOS 01: LVDS 10: LVPECL 11: LPHCSL		1
Bit 4	DIFF2_OUTPUT_TYPE[0]	Differential clock 2 type select bit 0	R/W			1
Bit 3	DIFF2_AMP[1]	Differential clock 2 amplitude control bit 1	R/W	LPHCSL: 00=740mV,01=800mV,10=855mV,11=910mV LVPECL:00=710mV,01=810mV,10=875mV,11=920mV LVDS:00=311mV,01=344mV,10=376mV,11=408mV		0
Bit 2	DIFF2_AMP[0]	Differential clock 2 amplitude control bit 0	R/W			1
Bit 1	DIFF2_CMOS_SLEW	Differential clock 2 LVCMOS slew rate control	R/W	normal	strong	0
Bit 0	DIFF2_CMOS2_EN	Differential clock 2 LVCMOS output_B control	R/W	disable	enable	0

Byte36: SE1 and DIV4 control

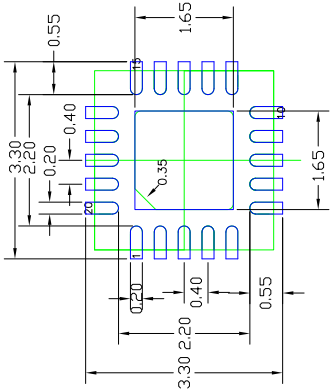
Byte 24h	Name	Control Function	Type	0	1	PWD
Bit 7	I2C_PDB	chip power down control bit	R/W	power down	normal	1
Bit 6	Ref_free_run	Reference clock output (SE2/SE3)	R/W	stop	freerun	0
Bit 5	free_run_output_config	SE clocks free run control	R/W	SE2 free run	SE2/3 free run	0
Bit 4	SE1_Freerun_32K	SE1 clock output default	R/W	32K freerun	B36bit3 control	0
Bit 3	SE1_CLKSEL1	SEL1 output select	R/W	DIV5	DIV4	1
Bit 2	REF_EN	REF output enable	R/W	disable	enable	1
Bit 1	DIV4_CH3_EN	DIV4 channel 3 output control	R/W	disable	enable	0
Bit 0	DIV4_CH2_EN	DIV4 channel 2 output control	R/W	disable	enable	0

Package Outline Drawings (NDG20)



Package Outline Drawings (NDG20), cont.

REVISIONS		
REV	DESCRIPTION	DATE
00	INITIAL RELEASE	3/30/16
		APPROVED
		JH

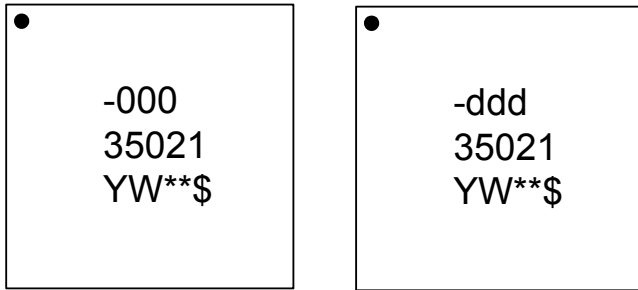


RECOMMENDED LAND PATTERN DIMENSION

- NOTES:
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
 2. TOP-DOWN VIEW, AS VIEWED ON PCB.
 3. COMPONENT OUTLINE SHOWS FOR REFERENCE IN GREEN.
 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
 5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPECIFIED	6024 Silver Creek Valley Road
DECIMAL ±1	San Jose, CA 95138
XX±	PHONE: (408) 284-8200
XXX±	FAX: (408) 284-8591
APPROVALS	www.IDT.com
DRAWN #24C	TITLE ND/NDG 20 PACKAGE OUTLINE
CHECKED	3.0 x 3.0 mm BODY, EPAD 1.65 mm SQ
	0.40 PITCH QFN
	SIZE DRAWING No.
	C PSC-4179-02
	REV
	00
	DO NOT SCALE DRAWING
	SHEET 2 OF 2

Marking Diagrams



Notes:

1. Line 1&2: truncated part number
2. "-000" denotes blank part.
3. "-ddd" denotes dash code.
4. "***" is the lot sequence number.
5. "YW" is the last digit of the year and week that the part was assembled.
6. "\$" is the mark code.

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
5P35021-000NDGI	Tubes	20-pin QFN	-40° to +85°C
5P35021-000NDGI8	Tape and Reel	20-pin QFN	-40° to +85°C
5P35021-dddNDGI	Tubes	20-pin QFN	-40° to +85°C
5P35021-dddNDGI8	Tape and Reel	20-pin QFN	-40° to +85°C

Revision History

Date	Description of Change
11/30/17	Updated I ² C section.
01/25/17	1. Corrected typos in Byte 27. 2. Updated package outline drawing.
09/20/16	Changed package outline drawing EPAD reference from 1.10mm to 1.65mm.
05/26/16	Initial release.



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JONHON

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«**FORSTAR**» (основан в 1998 г.)

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